CLAIMS

1. A tape for glass processing, the tape comprising a temporary adhesive tape having a substrate film and a temporary adhesive layer formed on at least one surface side of the substrate film,

wherein regarding the temporary adhesive tape, the sum of the average value of derivative values of the thermal deformation rate in the MD direction per 1°C between 40°C and 80°C as measured at the time of raising temperature by means of a thermomechanical characteristics testing machine, and the average value of derivative values of the thermal deformation rate in the TD direction per 1°C between 40°C and 80°C as measured at the time of raising temperature by means of a thermomechanical characteristics testing machine, is a negative value, and

the tape for glass processing is used for glass processing including an expansion step of expanding the temporary adhesive tape,

wherein the tape for glass processing is used for stealth dicing using a laser

wherein an adhesive layer is laminated on the temporary adhesive layer side, and the adhesive layer has a light transmittance of 90% or higher to light having a wavelength of 550 nm.

2. A tape for glass processing, the tape comprising a temporary adhesive tape having a substrate film and a temporary adhesive layer formed on at least one surface

side of the substrate film,

wherein the substrate film is formed of an ionomer resin or a mixed resin composition of polypropylene and a styrene-butadiene copolymer, and

regarding the temporary adhesive tape, the sum of the average value of derivative values of the thermal deformation rate in the MD direction per 1°C between 40°C and 80°C as measured at the time of raising temperature by means of a thermomechanical characteristics testing machine, and the average value of derivative values of the thermal deformation rate in the TD direction per 1°C between 40°C and 80°C as measured at the time of raising temperature by means of a thermomechanical characteristics testing machine, is a negative value,

wherein the tape for glass processing is used for stealth dicing using a laser

wherein an adhesive layer is laminated on the temporary adhesive layer side, and the adhesive layer has a light transmittance of 90% or higher to light having a wavelength of 550 nm.

~~3. The tape for glass processing according to claim 1 or 2, wherein an adhesive layer is laminated on the temporary adhesive layer side, and the adhesive layer has a light transmittance of 90% or higher to light having a wavelength of 550 nm.~~